SPUTTERING TARGET MATERIAL

Publication number:	WO02077317 (A1)	Also published as:	
Publication date:	2002-10-03		EP1371749 (A1)
Inventor(s):	HASEGAWA KOICHI [JP]; ISHII NOBUO [JP]; ASAKI TOMOYOSHI [JP] +		EP1371749 (B1) S2004055882 (A1) US7465424 (B2)
Applicant(s):	ISHIFUKU METAL IND [JP]; HASEGAWA KOICHI [JP]; ISHII NOBUO [JP]; ASAKI TOMOYOSHI		TW575674 (B)
	[JP] +		more >>
Classification:		С	ited documents:
- international:	C22C5/06; C22C5/08; C23C14/14; C23C14/34; G11B7/258; G11B7/26; C22C5/06; C23C14/14; C23C14/34; G11B7/24; G11B7/26; (IPC1- 7): C22C5/06; C23C14/14; C23C14/34; G09F9/30; G11B7/26; H05B33/10; H05B33/14; H05B33/24		JP2001357559 (A) JP11025515 (A) JP10177742 (A) JP2000109943 (A) JP9111380 (A)
- European:	C22C5/06; C22C5/08; C23C14/14; C23C14/34B2; G11B7/258D; G11B7/26		
Application number:	WO2002JP02466 20020315		
Priority number(s):	JP20010076132 20010316		

Abstract of WO 02077317 (A1)

A sputtering target material which comprises an Ag alloy comprising Ag, a specific small amount of a metal component (A) selected from among In, Sn and Zn and a specific small amount of a metal component (B) selected from among Au. Pd and Pt and optionally a small amount of Cu. The sputtering target material has a high reflectance and also exhibits excellent resistance to sulfurization.

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